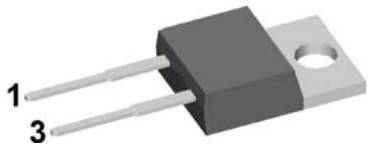
HiPerFRED²

V_{RRM} = 300 V
I_{FAV} = 10 A
t_{rr} = 35 ns

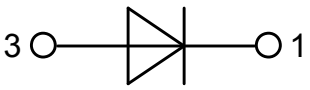
High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Single Diode

Part number

DPG10I300PA



Backside: cathode



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: TO-220

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

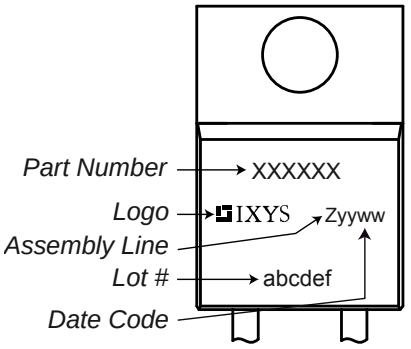
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Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			300	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			300	V
I_R	*reverse current, drain current*	V_R = 300 V	T_{VJ} = 25°C			1	µA
		V_R = 300 V	T_{VJ} = 150°C			0.06	mA
V_F	*forward voltage drop*	I_F = 10 A	T_{VJ} = 25°C			1.27	V
		I_F = 20 A				1.45	V
		I_F = 10 A	T_{VJ} = 150°C			0.98	V
		I_F = 20 A				1.17	V
I_{FAV}	*average forward current*	T_C = 150°C	T_{VJ} = 175°C			10	A
		rectangular d = 0.5					
V_{F0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 175°C			0.74	V
r_F	*slope resistance* }					17.7	mΩ
R_{thJC}	*thermal resistance junction to case*					2.3	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.50		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			65	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine; V_R = 0 V	T_{VJ} = 45°C			140	A
C_J	*junction capacitance*	V_R = 150 V f = 1 MHz	T_{VJ} = 25°C		15		pF
I_{RM}	*max. reverse recovery current*		T_{VJ} = 25°C		3		A
		I_F = 10 A; V_R = 200 V	T_{VJ} = 125°C		5.5		A
t_{rr}	*reverse recovery time*	$-di_F/dt$ = 200 A/µs	T_{VJ} = 25°C		35		ns
			T_{VJ} = 125°C		45		ns

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Package TO-220			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	*RMS current*	per terminal			35	A
T_{VJ}	*virtual junction temperature*		-55		175	°C
T_{op}	*operation temperature*		-55		150	°C
T_{stg}	*storage temperature*		-55		150	°C
Weight				2		g
M_D	*mounting torque*		0.4		0.6	Nm
F_C	*mounting force with clip*		20		60	N

Product Marking



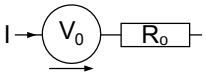
Part number

D = Diode
P = HiPerFRED
G = extreme fast
10 = Current Rating [A]
I = Single Diode
300 = Reverse Voltage [V]
PA = TO-220AC (2)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DPG10I300PA	DPG10I300PA	Tube	50	506640

Similar Part	Package	Voltage class
DPG10IM300UC	TO-252AA (DPak)	300

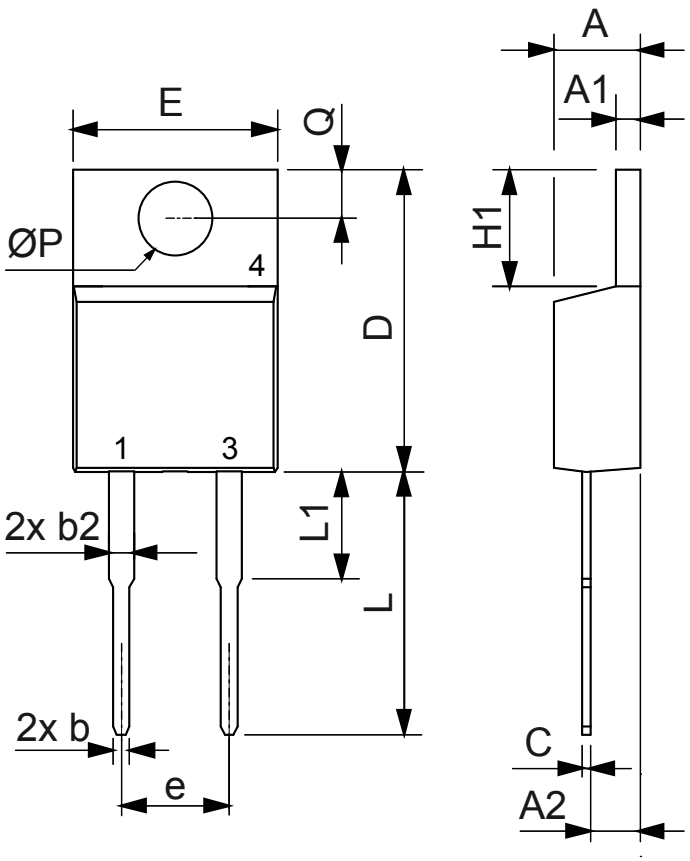
Equivalent Circuits for Simulation ** on die level* T_{VJ} = 175 °C



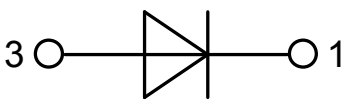
		Fast Diode	
$V_{0\,max}$	*threshold voltage*	0.74	V
$R_{0\,max}$	*slope resistance **	14.5	mΩ

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Outlines TO-220



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.32	4.82	0.170	0.190
A1	1.14	1.39	0.045	0.055
A2	2.29	2.79	0.090	0.110
b	0.64	1.01	0.025	0.040
b2	1.15	1.65	0.045	0.065
C	0.35	0.56	0.014	0.022
D	14.73	16.00	0.580	0.630
E	9.91	10.66	0.390	0.420
e	5.08	BSC	0.200	BSC
H1	5.85	6.85	0.230	0.270
L	12.70	13.97	0.500	0.550
L1	2.79	5.84	0.110	0.230
ØP	3.54	4.08	0.139	0.161
Q	2.54	3.18	0.100	0.125



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Fast Diode

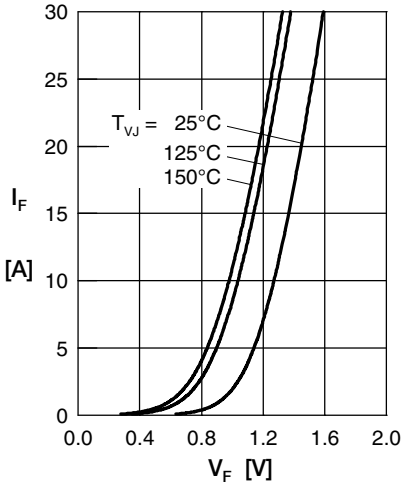


Fig. 1 Forward current I_F versus V_F

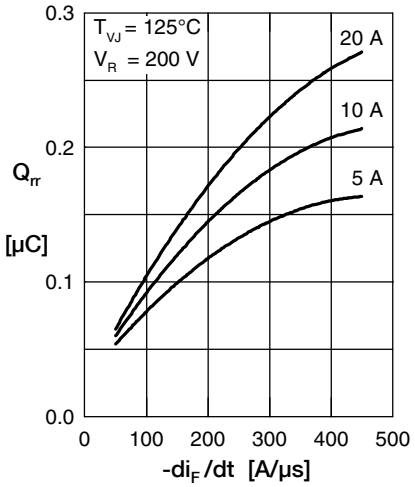


Fig. 2 Typ. reverse recov. charge Q_{rr} versus -di$_F$/dt

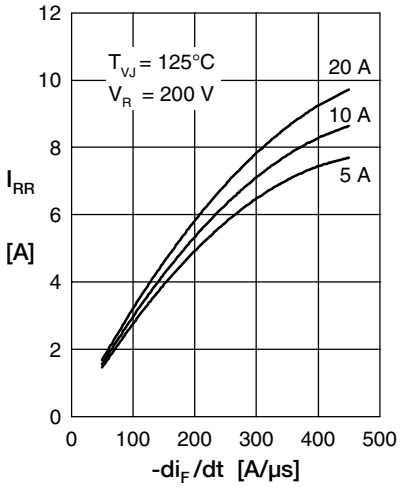


Fig. 3 Typ. reverse recov. current I_{RR} versus -di$_F$/dt

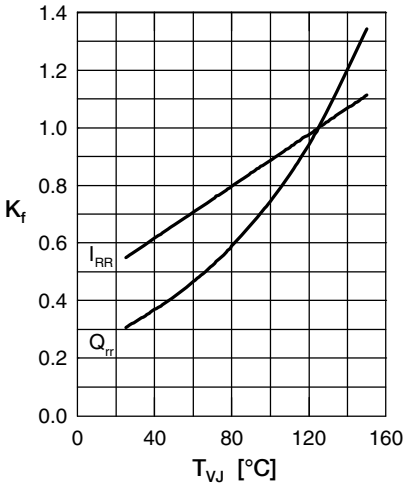


Fig. 4 Typ. dynamic parameters Q_{rr}, I_{RR} versus T_{VJ}

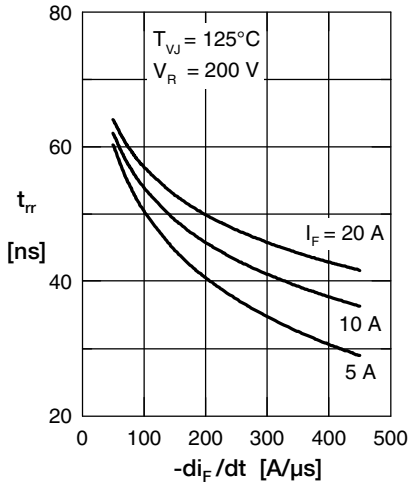


Fig. 5 Typ. reverse recov. time t_{rr} versus -di$_F$/dt

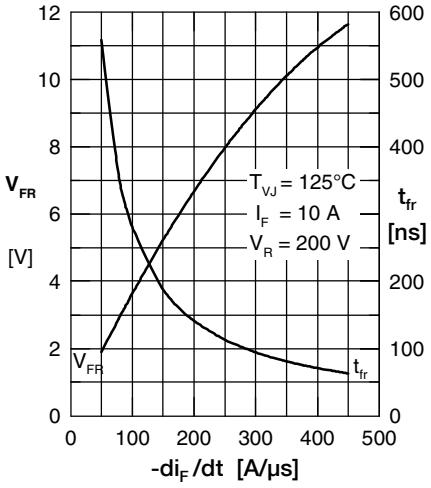


Fig. 6 Typ. forward recov. voltage V_{FR} and t_{fr} versus di$_F$/dt

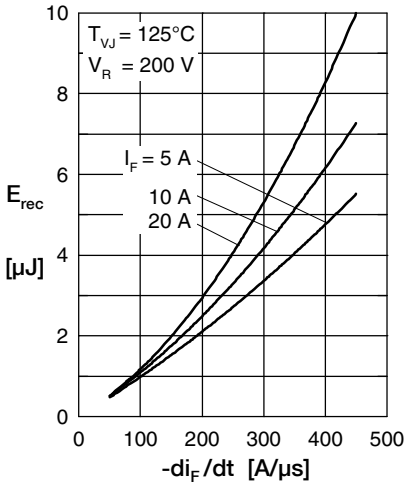
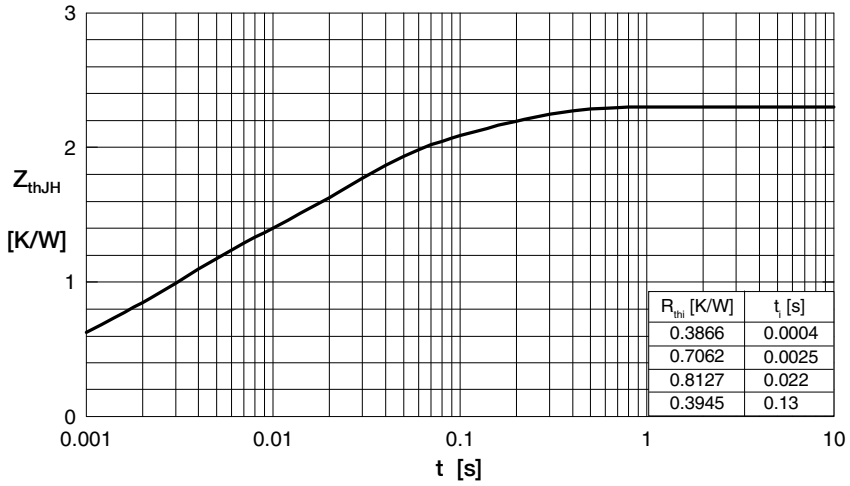


Fig. 7 Typ. recovery energy E_{rec} versus -di$_F$/dt



R_{thi} [K/W]	t_i [s]
0.3866	0.0004
0.7062	0.0025
0.8127	0.022
0.3945	0.13

Fig. 8 Transient thermal resistance junction to case

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